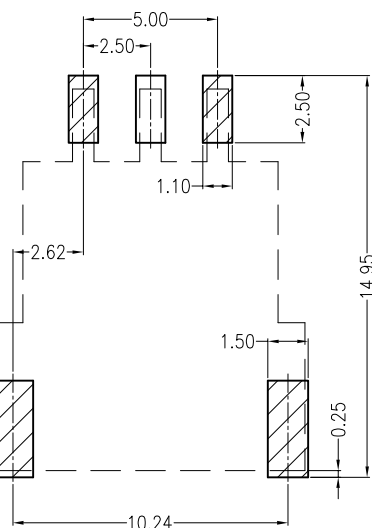
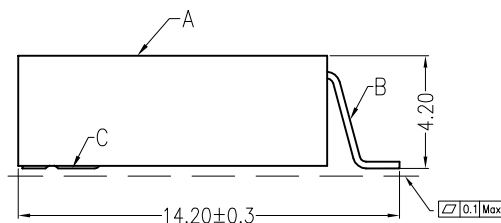
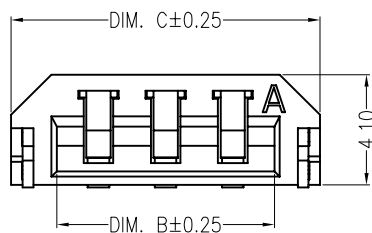
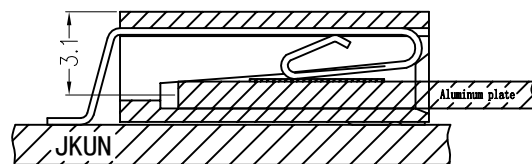


Mating Aluminum plate detail



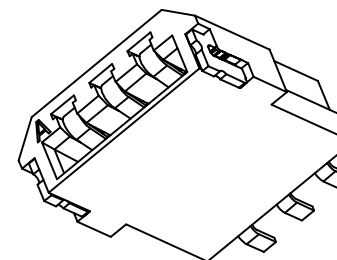
Board Layout

名称	尺寸	DIM=A	DIM=B	DIM=C
L006-02		2.50	5.60	9.00
L006-03		5.00	8.10	11.50



Assembly Layout

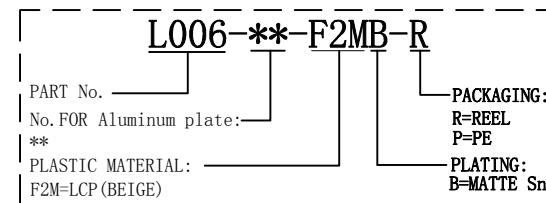
REV	ECN No.	DESCRIPTION	DESIGN	DATE
A0		Release	吴丹平	2014.03.18



主要技术参数 Main Specifications

- 板厚 (thickness): 1.0mm to 1.2mm
- 接触电阻 (Contact resistance): $\leq 20m\Omega$
- 绝缘电阻 (Insulation resistance): $\geq 800M\Omega$
- 额定电压 (Rated voltage): 250V AC DC
- 额定电流 (Rated current): 2.0A AC DC
- 耐电压 (Withstand Voltage): 800V AC/minute
- 温度范围 (Temperature Range): $-25^{\circ}C \sim +105^{\circ}C$

ORDER INFORMATION:



ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
C	SOLDER TAB	2 PCS	Brass	Sn-plated
B	CONTACT	2~3 PCS	PhosphorBronze	MATTE Sn-plated
A	PEDESTAL	1 PCS	LCP	UL 94V-0, COLOR:BEIGE

东莞市高迪电子有限公司 DONG GUAN GAO DI ELECTRONICS CO., LTD		TITLE: L006-**-1R 2.5mmPITCH 90°WAFER SMT TYPE	
X.±0.5	X.±5'	USE: CUSTOMER	PART NO.:
.X±0.3	.X±2'		L006-**-F2MB-R
.XX±0.25	.XX±1'	APPD: 邵敬和	DWG NO.:
--	--	CHKD: 田峰	GCCP-0015
UNITS: mm	DR: 吴丹平	SCALE: 1:1	SHEET: 1/1